

# Micro BGA

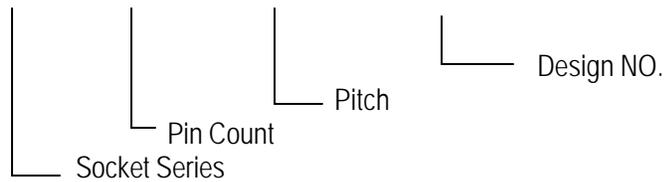
# BALL GRID ARRAY

Applicable IC/Micro BGA

## OPEN TOP TYPE SOCKETS

### ORDERING PROCEDURE

OTB - (        ) - (        ) - (        )

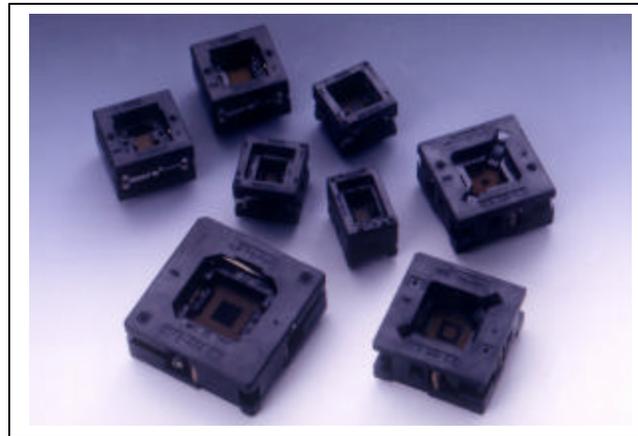


### SPECIFICATIONS

- Contact resistance: Initial  $50\text{m}\Omega$  (At 10mA)
- Maximum voltage: AC700V RMS (for 1 minute)
- Insulation resistance:  $1,000\text{M}\Omega$  or higher (At DC 500V)
- Rated current: 1A
- Operating temperature range:  $-60^{\circ}\text{C} \sim +150^{\circ}\text{C}$
- Terminal strength against pulling: 0.5kg (1 minute)
- Insertion: Min. 10,000 times (Mechanical)

### MATERIAL

- Body: PEI, PES
- Contact: BeCu, Au plating (Ni-base)



## APPLICABLE IC DIMENSIONS & SOCKET DIMENSIONS

### OTB-192 SERIES (0.8mm PITCH)

Unit: mm

PART NO.	APPLICABLE IC DIMENSIONS (REF.)					OUTSIDE DIMENSIONS (REF.)				REMARKS
	BODY SIZE	GRID	ROW/ARRAY	LEADS NUMBER	PITCH	A	B	C	D	
OTB-54(192)-0.8-06	8X12	9X9	Depopulated	54	0.8	24	20	17.1	2.7	
OTB-128(192)-0.8-03	11X11	12X12	P.4 ROW	128	0.8	24	20	17.1	2.7	

